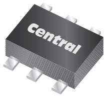
Material Composition Specification

SOT-963 Case



Device average mass . . . . 1.195 mg

Fluctuation margin . . . . +/-10%

Component	Material	Material		Substance	CAS No.	Substance		
		(%wt)	(mg)			(%wt)	(mg)	(ppm)
active device	doped Si	2.51%	0.03	Si	7440-21-3	2.51%	0.03	25,109
bond wire	gold	1.26%	0.015	Au	7440-57-5	1.26%	0.015	12,554
leadframe	Cu alloy	42.87%	0.5122	Cu	7440-50-8	41.93%	0.501	419,317
				Fe	7439-89-6	0.92%	0.011	9,207
				P	7723-14-0	0.01%	0.0001	84
				Zn	7440-66-6	0.01%	0.0001	84
die attach	silver epoxy	1.17%	0.014	Ag	7440-22-4	1.0%	0.012	10,044
				resin filler	Proprietary	0.17%	0.002	1,674
encapsulation	EMC	50.8%	0.607	amorphous silica	7631-86-9	49.21%	0.588	492,133
				epoxy resin	Proprietary	1.51%	0.018	15,065
				carbon	1333-86-4	0.08%	0.001	837
plating	Ni/Pd/Au	1.39%	0.0166	Ni	7440-02-0	1.34%	0.016	13,391
				Pd	7440-05-3	0.01%	0.0001	84
				Au	7440-57-5	0.04%	0.0005	418

R2 (3-June 2011)